L Number	Hits	Search Text	DB	Time stamp
1	57549	Kondo.inv.	USPAT;	2003/09/30
			US-PGPUB;	13:14
			EPO; JPO;	
			DERWENT:	
			IBM_TDB	
2	4	Kondo .inv. and thermal near expansion and	USPAT;	2003/09/30
	_	mounting near apparatus	US-PGPUB;	13:15
	1		EPO; JPO;	
		,	DERWENT;	
			IBM_TDB	
3	36	IIZAKA near ATSUSHI .inv.	USPAT;	2003/09/30
J	30	ILAKA ileai A1000III illivi	US-PGPUB;	13:17
			EPO; JPO;	13.17
			DERWENT;	
			IBM_TDB	
	0	IIZAKA near ATSUSHI .inv. and mouting	USPAT;	2003/09/30
4	U	_	US-PGPUB;	13:17
		near apparatus	1	13:17
			EPO; JPO;	
			DERWENT;	
:		5400055	IBM_TDB	0000/00/07
•	2	5199855.pn.	USPAT;	2003/09/27
		·	US-PGPUB;	10:59
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	16	mounting adj system and frame and driver	USPAT;	2003/09/26
		and positioning near device and image adj	US-PGPUB;	07:32
		taking	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	5	mounting adj system and frame and driver	USPAT;	2003/09/30
		and image adj taking and thermal adj	US-PGPUB;	13:14
		expansion	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	0	component adj mounting near apparatus	USPAT;	2003/09/26
		and frame and driver and thermal adj	US-PGPUB;	07:11
		expansion near system	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	2	component adj mounting and frame and	USPAT;	2003/09/26
		driver and thermal adj expansion near	US-PGPUB;	07:11
		system	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
• i	0	component near apparatus and frame and	USPAT;	2003/09/26
		driver and thermal adj expansion near	US-PGPUB;	07:12
		system	EPO; JPO;	-
			DERWENT;	
			IBM_TDB	

			HODAT	0000/00/05
-	2	c mponent near mounting and frame and	USPAT;	2003/09/26
		driver and thermal adj expansion near	US-PGPUB;	07:12
		system	EP ; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	component near mounting and frame and	USPAT;	2003/09/26
		thermal adj expansion near system	US-PGPUB;	07:12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	3	component near mounting and thermal adj	USPAT;	2003/09/26
		expansion near system	US-PGPUB;	07:12
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	947	component near mounting and thermal adj	USPAT;	2003/09/26
		expansion	US-PGPUB;	07:13
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	0	component near mounting and thermal adj	USPAT;	2003/09/26
		expansion and image adj taken near device	US-PGPUB;	07:13
	1	expansion and image adjusted near device	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
_	10	component poor mounting and thormal adi	i –	2003/09/26
-	"	expansion and image adj taking	nent near mounting and thermal adj USPAT;	07:15
		expansion and image adjusting	US-PGPUB;	07:13
]		EPO; JPO;	
			DERWENT;	
	26	20/740 cala and the amount many assessment	IBM_TDB	2002/00/20
-	36	29/740.ccls. and thermal near expansion	USPAT;	2003/09/26
			US-PGPUB;	07:16
			EPO; JPO;	
			DERWENT;	
		040/0001-	IBM_TDB	0000100100
-	554	318/600.ccls.	USPAT;	2003/09/26
			US-PGPUB;	07:32
	1		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	2	6519835.pn.	USPAT;	2003/09/27
	1		US-PGPUB;	11:12
			EPO; JPO;	
	1		DERWENT;	
			IBM_TDB	
•	14241172	JP 05241660.pn.	USPAT;	2003/09/29
			US-PGPUB;	15:07
<u> </u>			EP ; JPO;	
			DERWENT;	
			IBM_TDB	

	3	thermal adj expansion near ballscrew and	USPAT;	2003/09/29
		mounting	US-PGPUB;	15:15
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
•	49	thermal adj expansion near mounting and	USPAT;	2003/09/29
		apparatus	US-PGPUB;	15:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
	2	thermal adj expansion near mounting and	USPAT;	2003/09/29
		apparatus and 29/\$.ccls.	US-PGPUB;	15:19
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	47	thermal adj expansion and mounting near	USPAT;	2003/09/29
		apparatus and 29/\$.ccls.	US-PGPUB;	15:20
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	7	("4222036" "5383270" "5768759"	USPAT	2003/09/29
		"5992013" "6101709" "6195454"		15:25
		"6216341").PN.		
-	1	"4747198".PN.	USPAT	2003/09/29
				15:27